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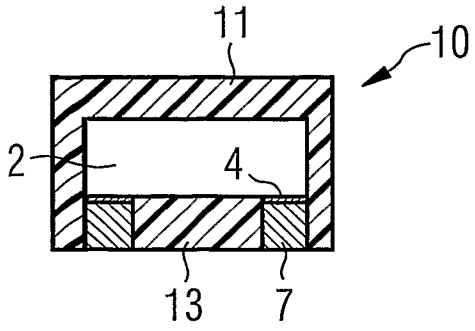
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WO 2005/078789 A1

(54) Title: CHIP-SIZED FILP-CHIP SEMICONDUCTOR PACKAGE AND METHOD FOR MAKING THE SAME



(57) Abstract: A semiconductor package (10; 14) comprises a semiconductor die (2; 2') with a plurality of contact areas (4) on its active surface and an electrically conductive bump (7) on each contact area (4). The die (2; 2') and electrically conductive bumps (7) are encapsulated in a plastic housing (11) so that the plastic housing (11) encapsulates at least sides of the die (2; 2') and sides of the electrically conductive bumps (7).